

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	1.43636	100.0	1.7
			Subtotal	1.43636	100	1.7
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.08871	99.99	0.10499
			Subtotal	0.08872	100	0.105
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02579	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05158	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.18639	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.31834	97.55	59.55427
			Subtotal	51.5821	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.4816	100.0	0.57
			Subtotal	0.4816	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.68349	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.3288	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.09835	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45566	1.0	0.5393
			Subtotal	45.5663	100	53.93
Die Attach		Aromatic Polyester Resin	60088-52-0	0.02112	2.5	0.025
		Paraffin wax	8002-74-2	0.05914	7.0	0.07
		Epoxy resin system		0.16898	20.0	0.2
		Silver (Ag)	7440-22-4	0.59567	70.5	0.705
			Subtotal	0.84491	100	1
			Total	99.99999	100	118.355

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